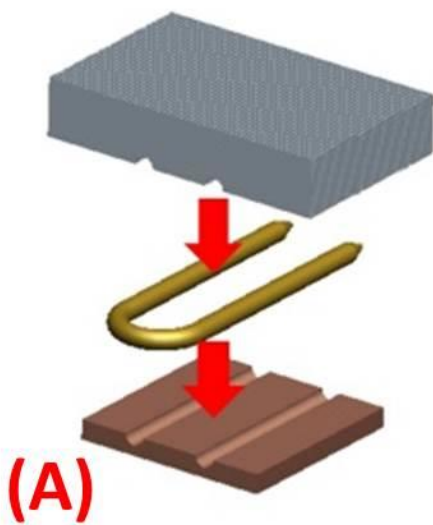## Fin/Pipe/Base Riveting

Sandwiched base/pipe/fin architecture (Fig. A) is often seen in DT (Fig. B) or play station heatsinks. The pipe/base riveting and base/fin swaging are done simultaneously by a stamping machine under a high precision die. Processing is simple and throughput is high. In this case, pipe is not contact to CPU or heat source directly.

(A)

(B)

Another fin/pipe/fancover sandwiched architecture (Fig. C) is commonly used in NB module. (Fig. D).   Flattened pipe is riveted onto fin surface first and   then fancover is riveted with pipe or fin together. Processing is simple with high throughput.

(C)

(D)